DATE: 11/20/15

"A" INTERFACE
FULL DETENT
SMOOTH BORE

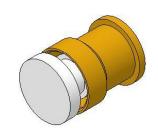
MATERIAL AND FINISH

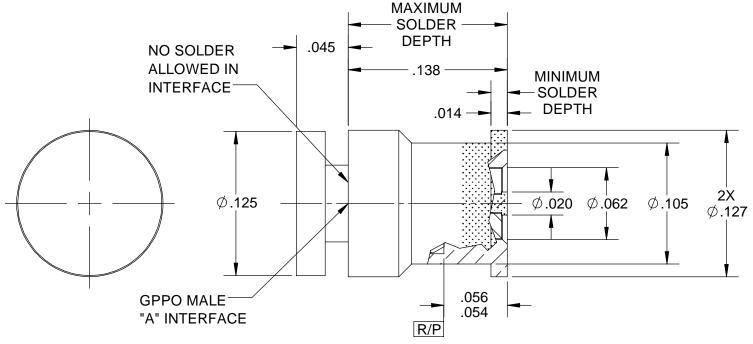
CENTER CONTACT AND SHROUD:

BeCu; GOLD PLATE 75 MICROINCHES TYPICAL OVER NICKEL PLATE 100 MICROINCHES TYPICAL

DIELECTRIC: POLYAMIDE-IMIDE

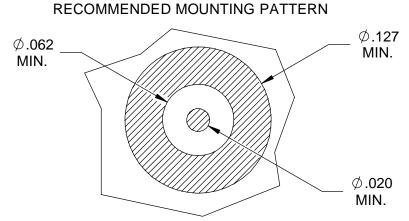
ALIGNMENT PLUG: VIRGIN PTFE





NOTES:

ALL DIMENSIONS APPLY PRE-SOLDER DIP UNLESS OTHERWISE SPECIFIED.



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	APPROX. WEIGHT:	0.1270	grams	SIGNATU	RES	INIT	DATE:	
n	TOLERANCE: .XX ±.010 .XXX ±.005 ANGULAR ±5°			DRAWN:	DMG		11/20/15	
;				CHECKED:	BLK			
				APPROVED:	TEF			•

GPPO MALE PCB SURFACE MOUNT SOLDER DIPPED (TAB DETENT)

CAGE CODE: SCALE: 12:1 82316

REVISION: 01

CORNING PHOENIX PLANT: (623)245-1050 CUSTOMER SERVICE: (800) 651-8869

PLANT OF ORIGIN

SOURCE ASSY. SK-4969 OL-B012-T7X-01-T DWG. NO.: FILE: PROC.